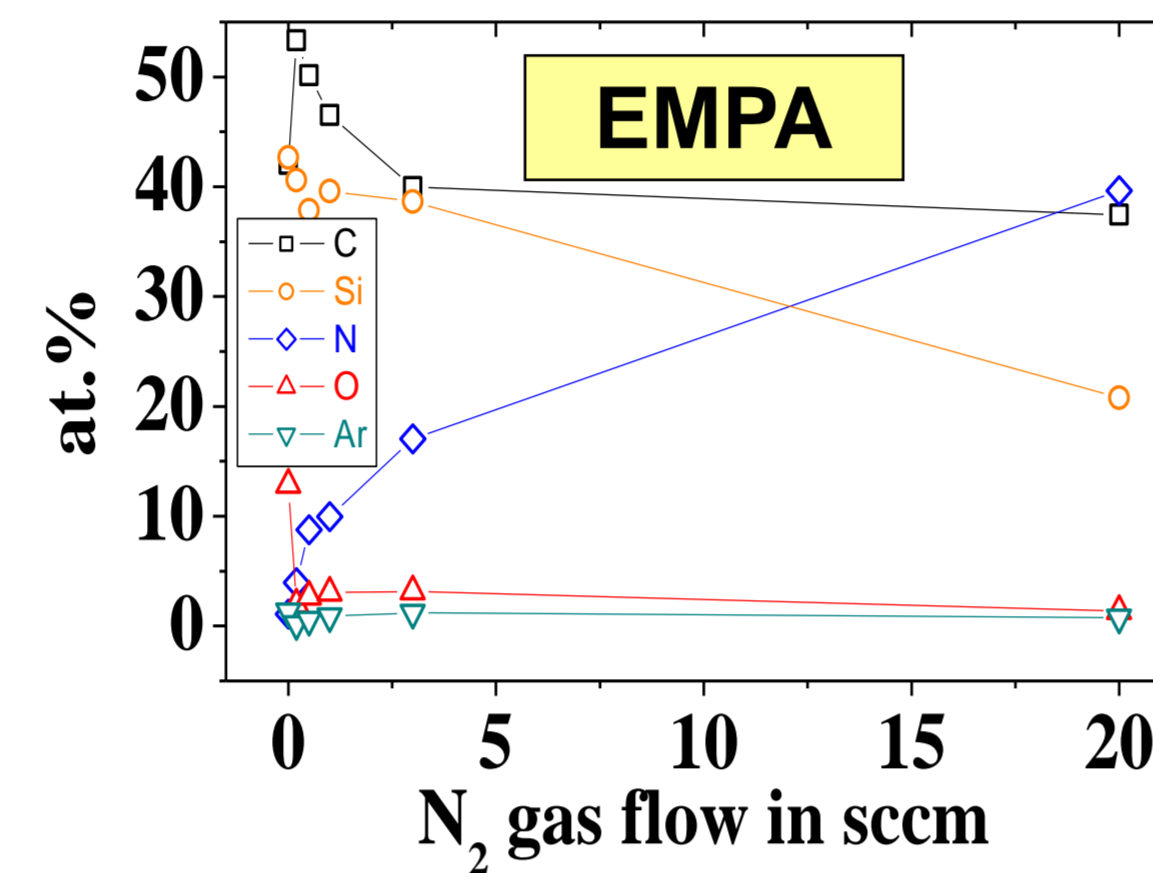


Sputter deposition of single layer Si-C-N films: molecular dynamics simulation and experimental validation of structure-property-correlations

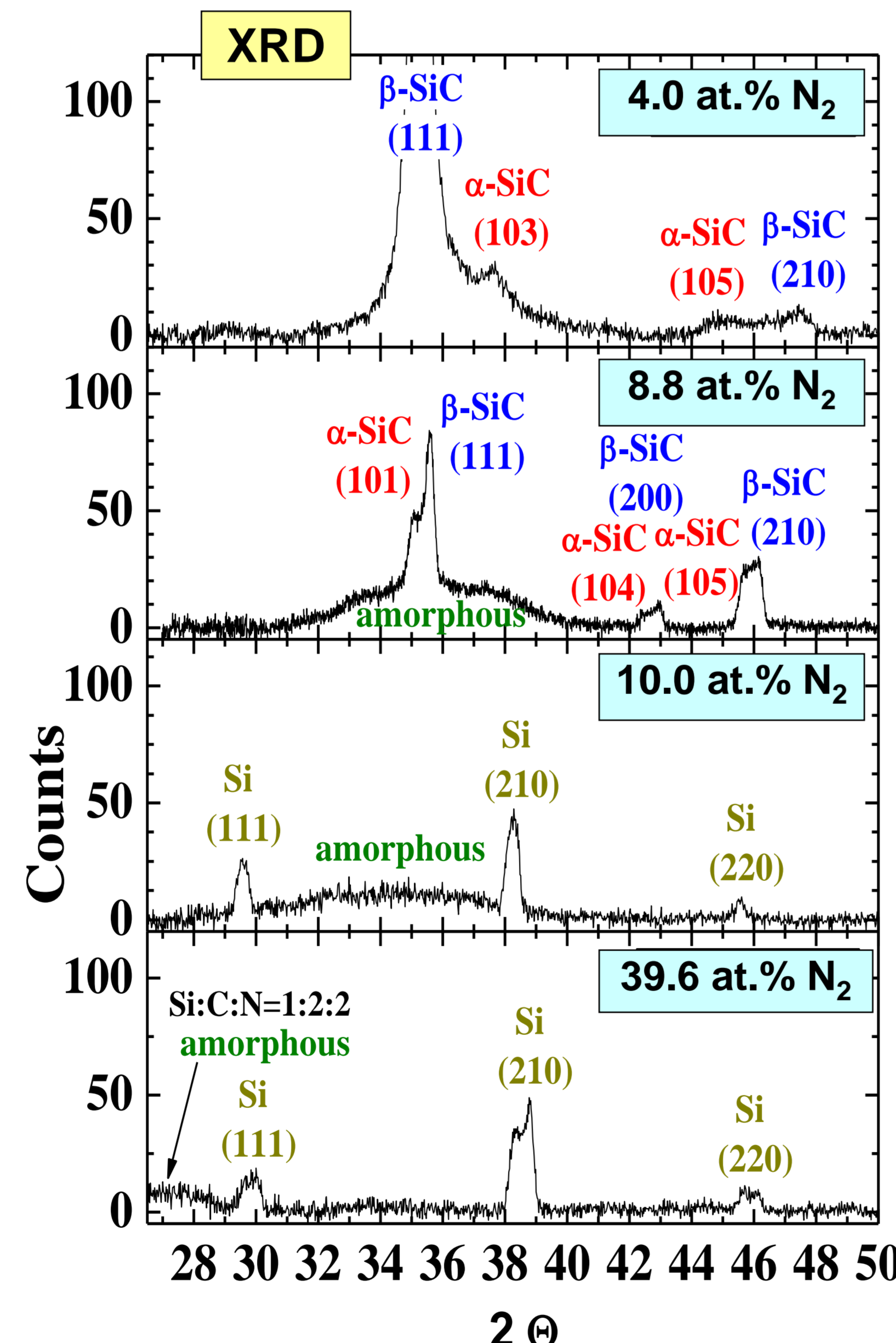
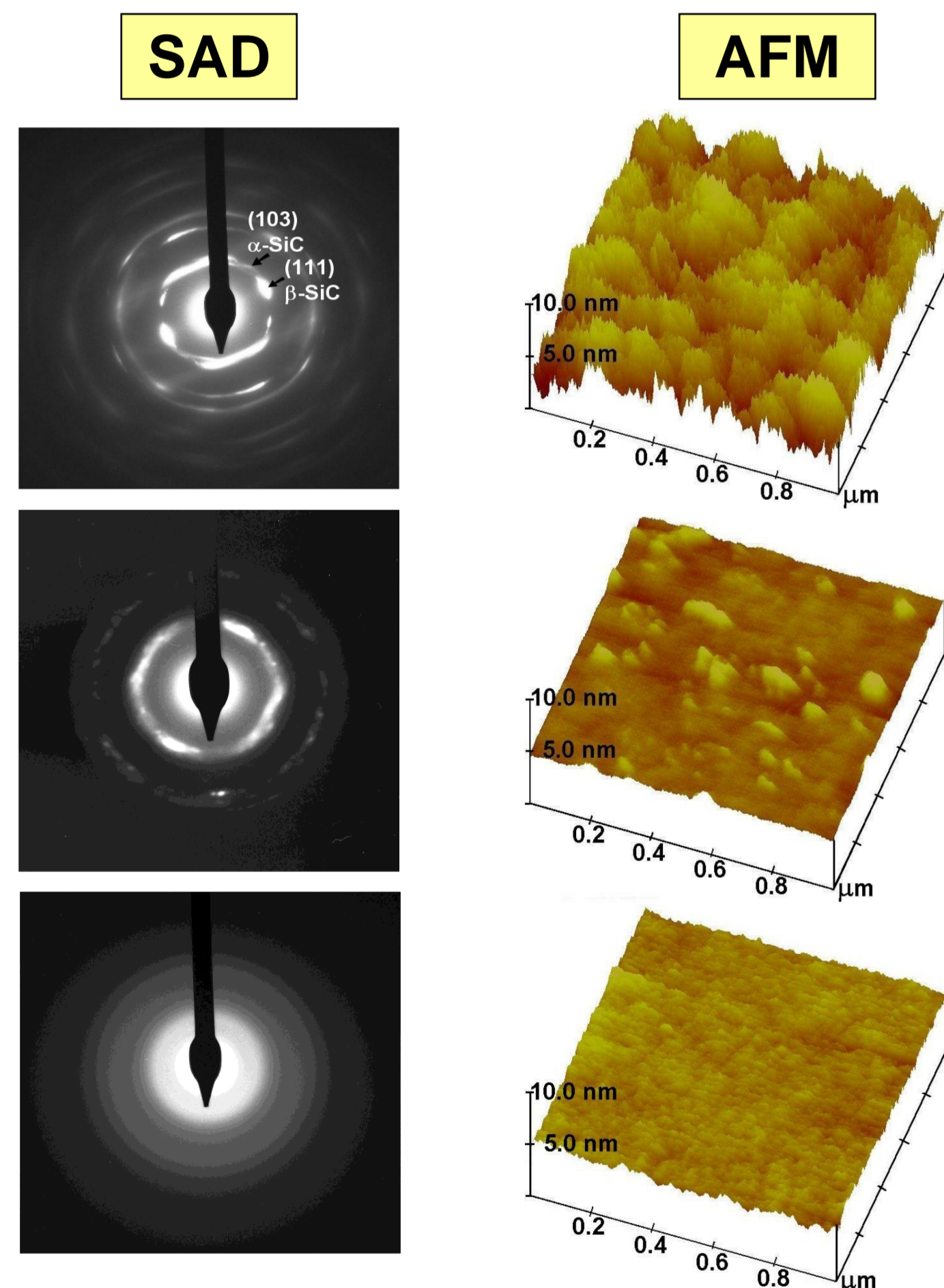
Experimental results

Preparation and Composition

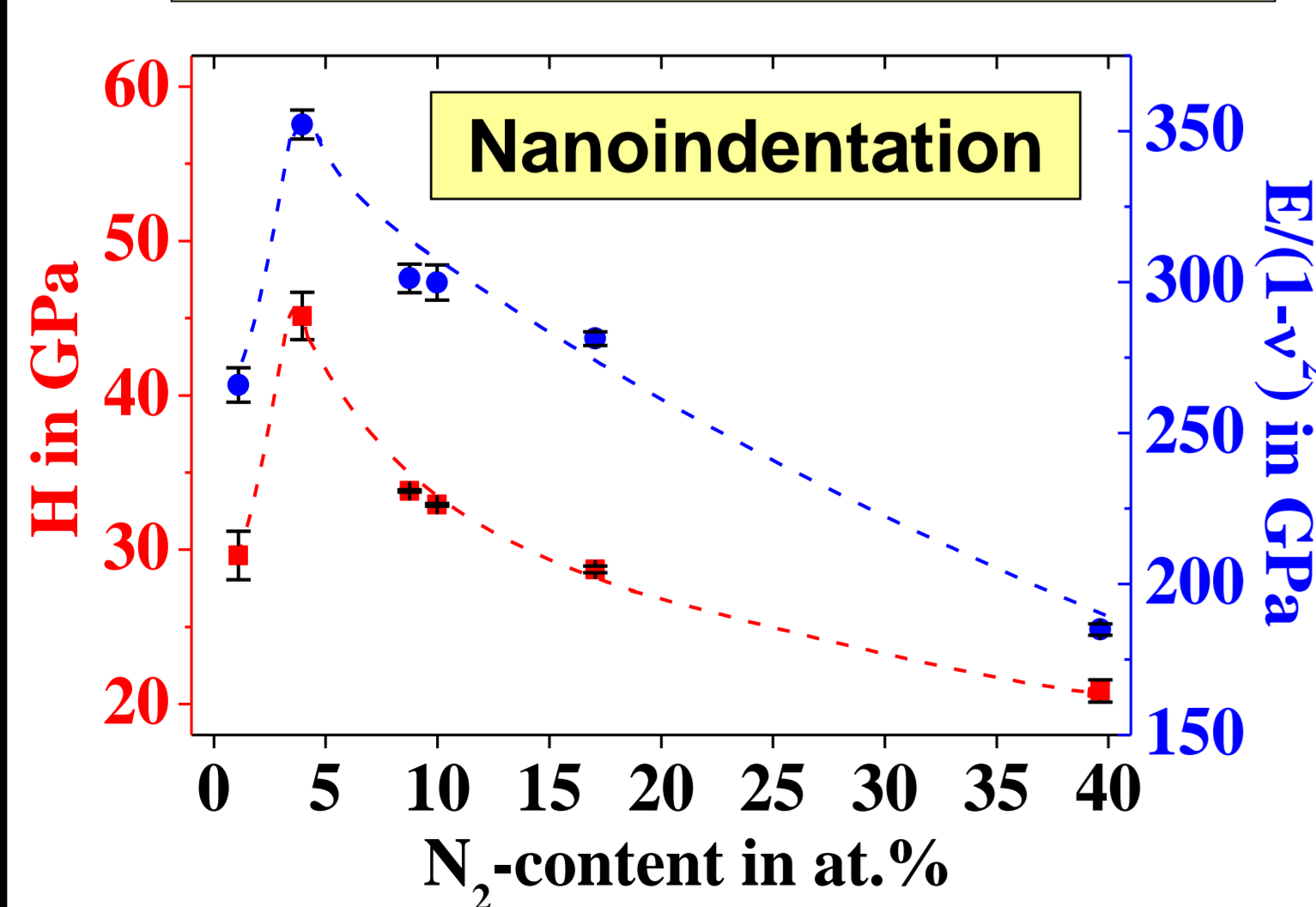
- RF magnetron sputtering from a SiC target in an Ar/N₂ atmosphere (T_s = 800 °C, U_s = 0 V) on Si and hard metal substrates with N₂ gas flow variation (0-20 sccm)
- Correlation of constitution, microstructure and properties



Microstructure and surface topography



Mechanical properties



Acknowledgement

This work was supported by the German Science foundation (DFG) in the project ZI 1174/3-1/SCHM 746/68-1

Molecular dynamics simulations

Sputtering

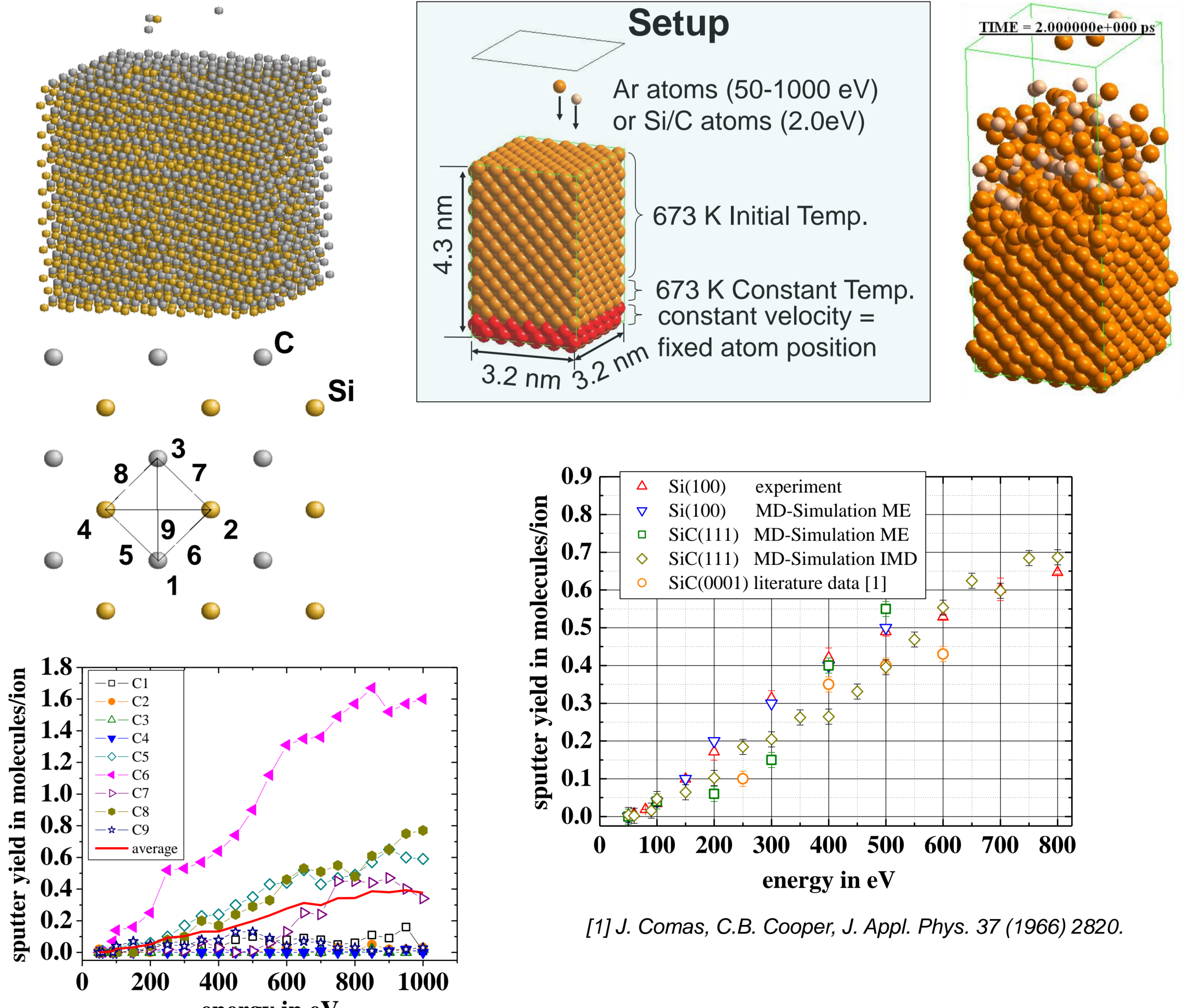
Target: C-terminated SiC, T_s = 673 K, potential: Tersoff
 x,y-axis: periodic boundary condition
 z-axis: open surface
 - 3072 Si atoms, 3072 C atoms (ME software)
 - 8000 Si atoms, 8000 C atoms (IMD software)

Ar: energy: 50-1000 eV, potential: ZBL, angle: 180°
 - 1 Ar at random every 24 ps, ensemble: NTV, Nosé thermostat (ME)
 - equilibration at 673K using NPT-simulation
 1 Ar on 9 coordinates for 50 thermally equivalent samples using NVE ensemble (IMD)

Deposition

Substrate: 2592 Si atoms, T_s = 673 K, potential: Tersoff
 x,y-axis: periodic boundary condition
 z-axis: open surface (ME)

Si/C: 1 Si/C atom every 1.25 ps, incidence angle: 180°, energy: 2 eV
 Number of deposited atoms: 800
 MD step: 1 fs, ensemble: NTV (ME)



Conclusions

As the first experimental step thin Si-C-N films have been deposited with systematic variation of the N₂ flow rate and its influence on the constitution, the microstructure and the mechanical properties was investigated. At a low N₂ content of 4.0 at.% in the film, a two-phase microstructure with nanocrystalline grains of 5-10 nm is formed with a hardness value of 45 GPa is formed.

As the first simulation step the sputtering of a SiC-target at 673 K by argon was simulated using the Tersoff potential for the Si-C interaction and ZBL pair potential for the interaction with argon and the sputter yield and the and the ranges of Ar ions and sputtered Si and C atoms were determined as a function of the energy of the incident Ar atoms.